APRIL 1982

JEDEC STANDARD No. 1

LEADLESS CHIP CARRIER PINOUTS

STANDARDIZED

FOR

LINEAR'S

FORMULATED BY

JEDEC SOLID STATE PRODUCTS ENGINEERING COUNCIL

JEDEC STANDARD No. 1

NOTICE

This JEDEC Standard contains material which has been prepared and progressively reviewed and approved through the JEDEC Council level and subsequently reviewed and approved by the EIA General Counsel.

JEDEC Standards are designed to serve the public interest through eliminating misunderstandings between manufacturers and purchasers, facilitating interchangeability and improvement of products, and assisting the purchaser in selecting and obtaining with minimum delay the proper product for his particular need. Existence of such standards shall not in any respect preclude any member or non-member of JEDEC from manufacturing or selling products not conforming to such standards, nor shall the existence of such standards preclude their voluntary use by those other than EIA members whether the standard is to be used either domestically or internationally.

JEDEC Standards and Publications are adopted by JEDEC without regard to whether or not their adoption may involve patents or articles, materials, or processes. By such action JEDEC does not assume any liability to any patent owner, nor does it assume any obligation whatever to parties adopting the JEDEC Standards or Publications.

The information included in JEDEC Standards represents a sound approach to product specification and application, principally from the solid state device manufacturer viewpoint. Within the JEDEC organization there are procedures whereby a JEDEC Standard may be further processed and ultimately become an EIA Standard.

Inquiries, comments, and suggestions relative to the content of this JEDEC Standard should be addressed to the JEDEC Executive Secretary at the EIA Headquarters.

JEDEC
Electronic Industries Association
2001 Eye Street N.W.
Washington, D.C. 20006

Published by

ELECTRONIC INDUSTRIES ASSOCIATION
Engineering Department
2001 Eye Street, N.W.
Washington, D.C. 20006

PRICE: $5.00

Printed in U.S.A.

JEDEC STANDARD No. 1

LEADLESS CHIP CARRIER PINOUTS STANDARDIZED FOR LINEAR'S

This JEDEC Standard was formulated under the cognizance of the JEDEC JC-41 Committee on Linear Integrated Devices.

NOTE: Numbering of JEDEC Standards follows a numerical sequence which does not necessarily relate to the publication date of the document.

LEADLESS CHIP CARRIER PINOUTS STANDARDIZED FOR LINEAR'S

The following criteria shall be used to convert existing DIP pin-outs for op-amps, comparators, and D/A converters, to chip carrier packages:

A. Chip Carrier Packages to be used shall be either the:

(1) 20-lead, .350" x .350", Type C package, or the

(2) 28-lead, .450" x .450", Type C package

B. Device Conversion shall be as follows:

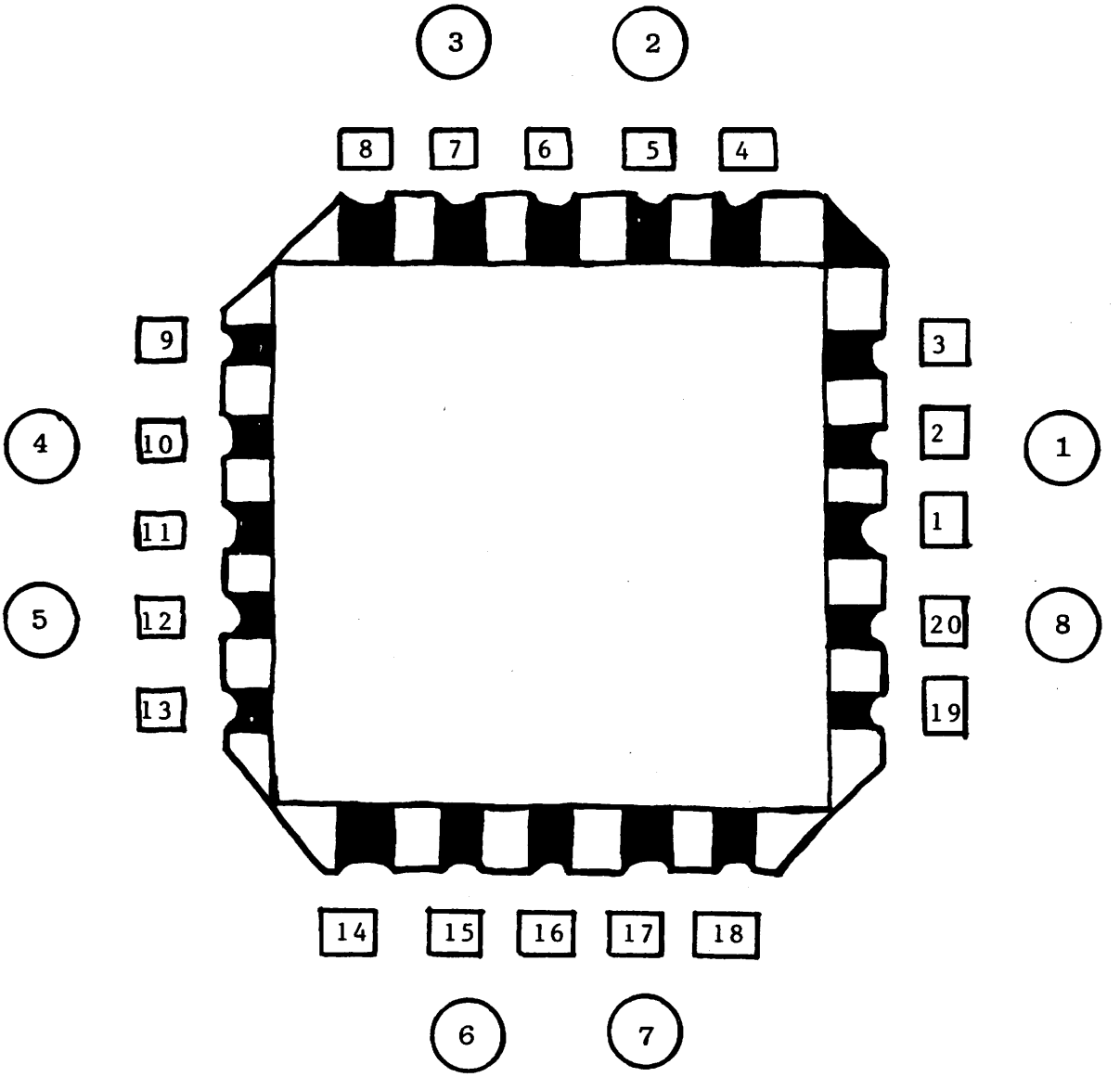
DIP PACKAGE	CHIP CARRIER PACKAGE
8 - LEAD 14 - LEAD 16 - LEAD 18 - LEAD 20 - LEAD	20 - LEAD
24 - LEAD 28 - LEAD	28 - LEAD

C. The pin-out conversions shall be in accordance with the diagram shown in Figures 1 through 6. Each device shall be pinned out based on it's present package/pinout.

Thus a part now in a 8 lead package shall be pinned out in accordance with the 8 lead conversion to 20 lead chip carrier. If a part is presently available in more than one pinout then it's lowest pin count package will be used to define the conversion to chip carrier pinouts. The single exception to this rule is 10 lead parts. They are also always available in 14 lead versions and will therefore use the 14 lead conversion.

The "optional" version of the 16 lead conversion is to be used only when the "preferred" version will not work. It's use is discouraged.

D. Devices presently in 20 and 28 lead packages shall be pinned out 1:1 in leadless chip carriers.



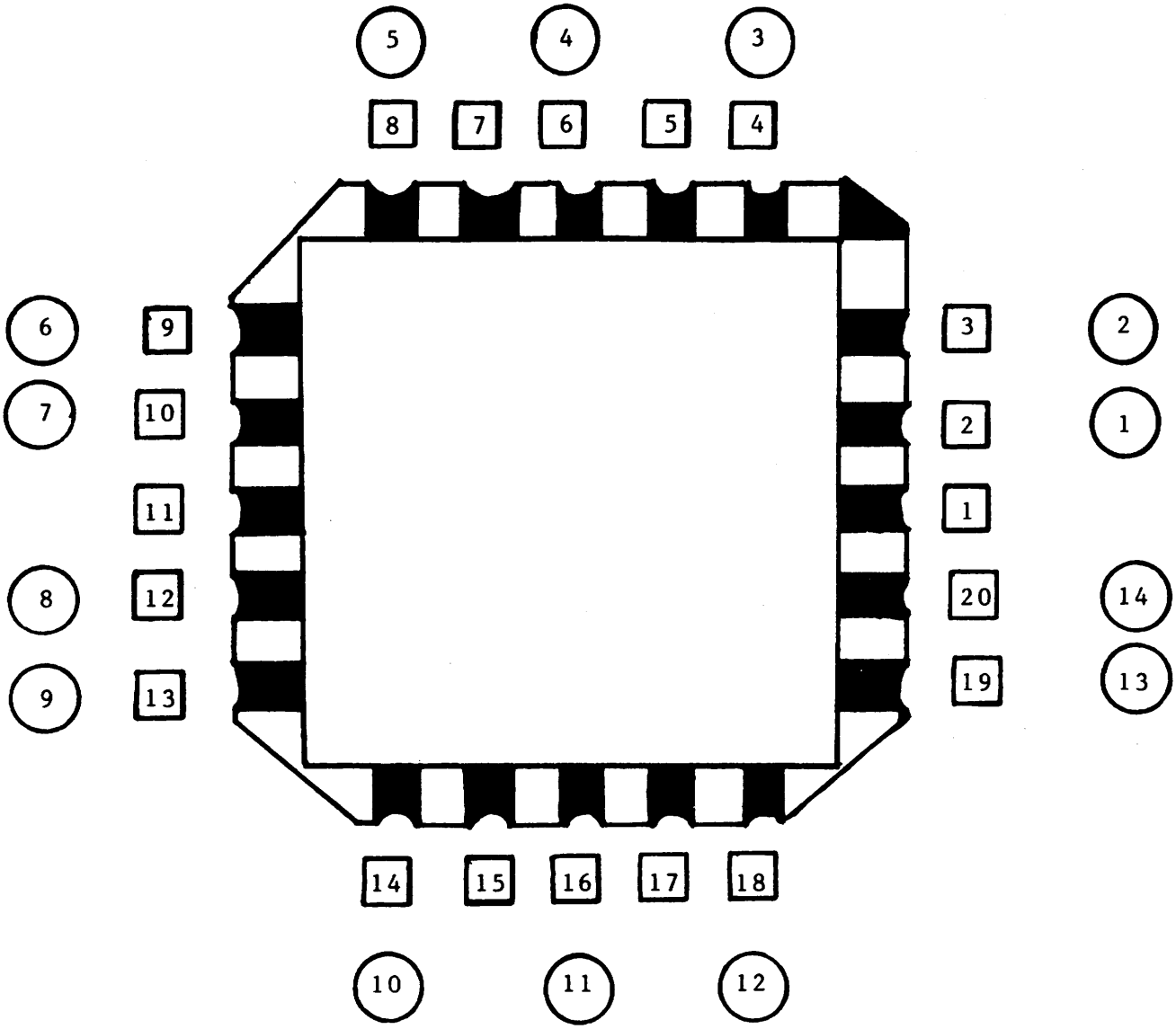
8 - LEAD PIN-OUT

FOR

20 - LEAD CHIP CARRIER

(Top View)

FIGURE 1



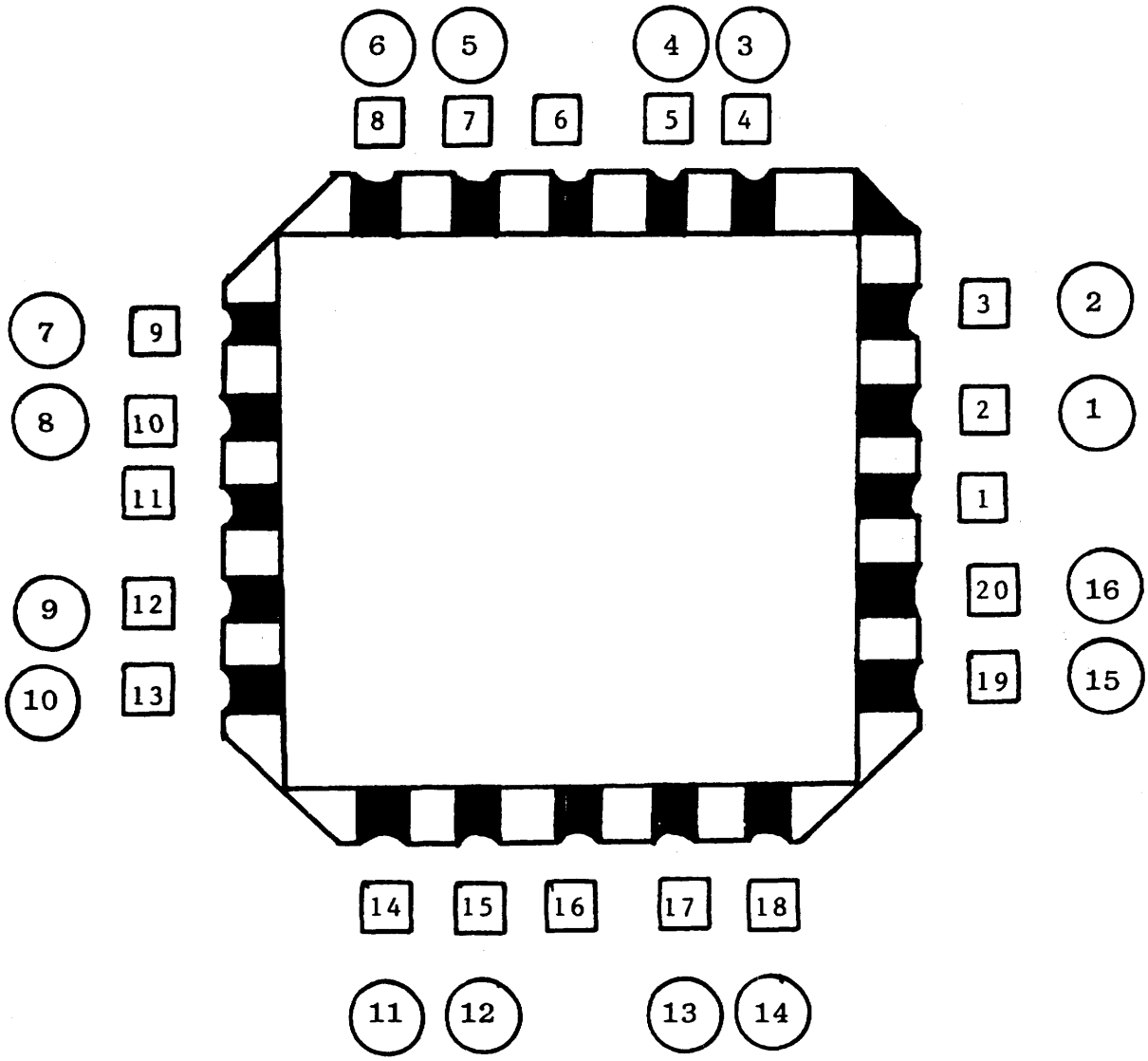
14 - LEAD PIN-OUT

FOR

20 - LEAD CHIP CARRIER

(Top View)

FIGURE 2



16 - LEAD PIN-OUT

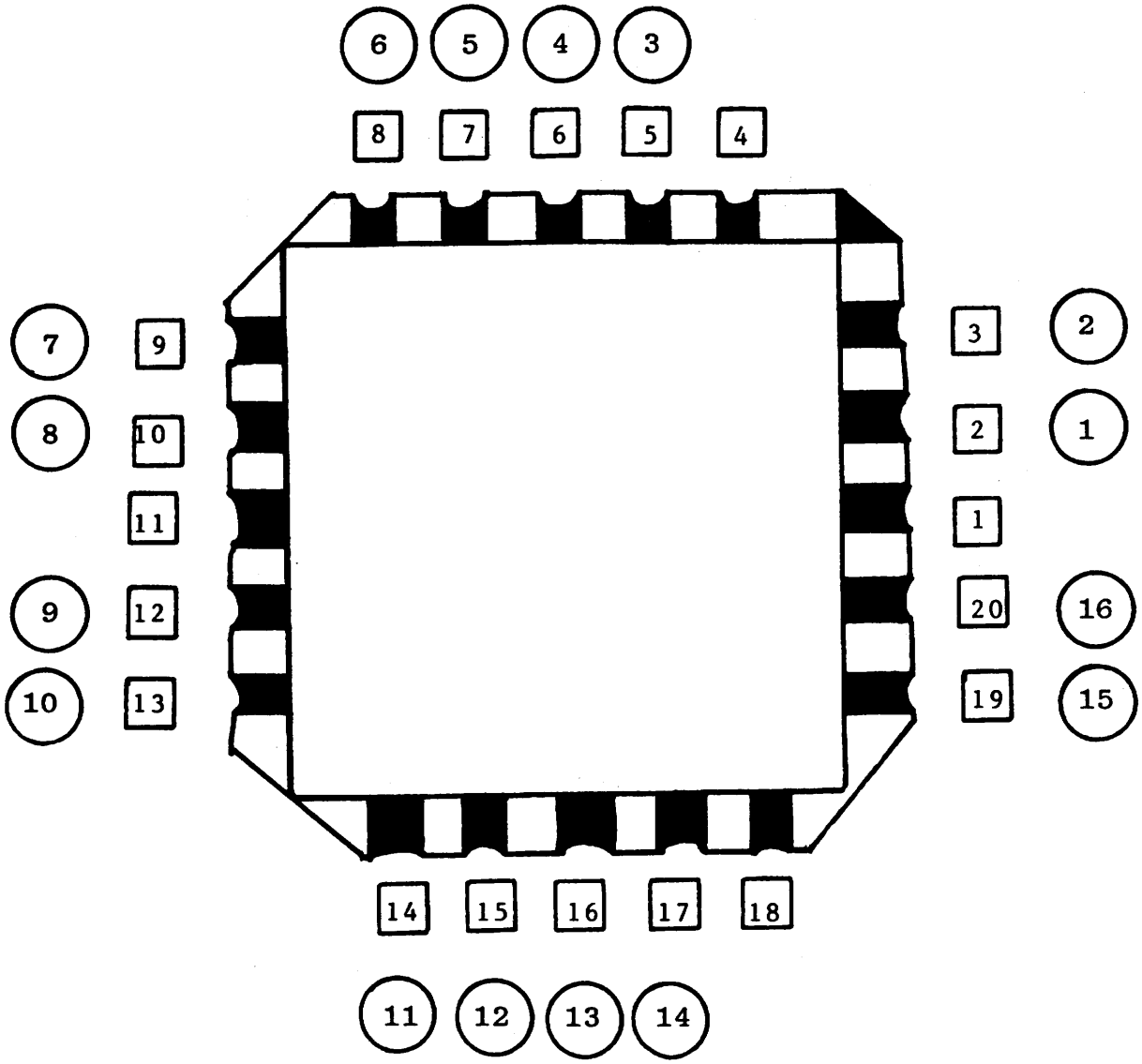
FOR

20 - LEAD CHIP CARRIER

(PREFERRED VERSION)

(Top View)

FIGURE 3



16 - LEAD PIN-OUT

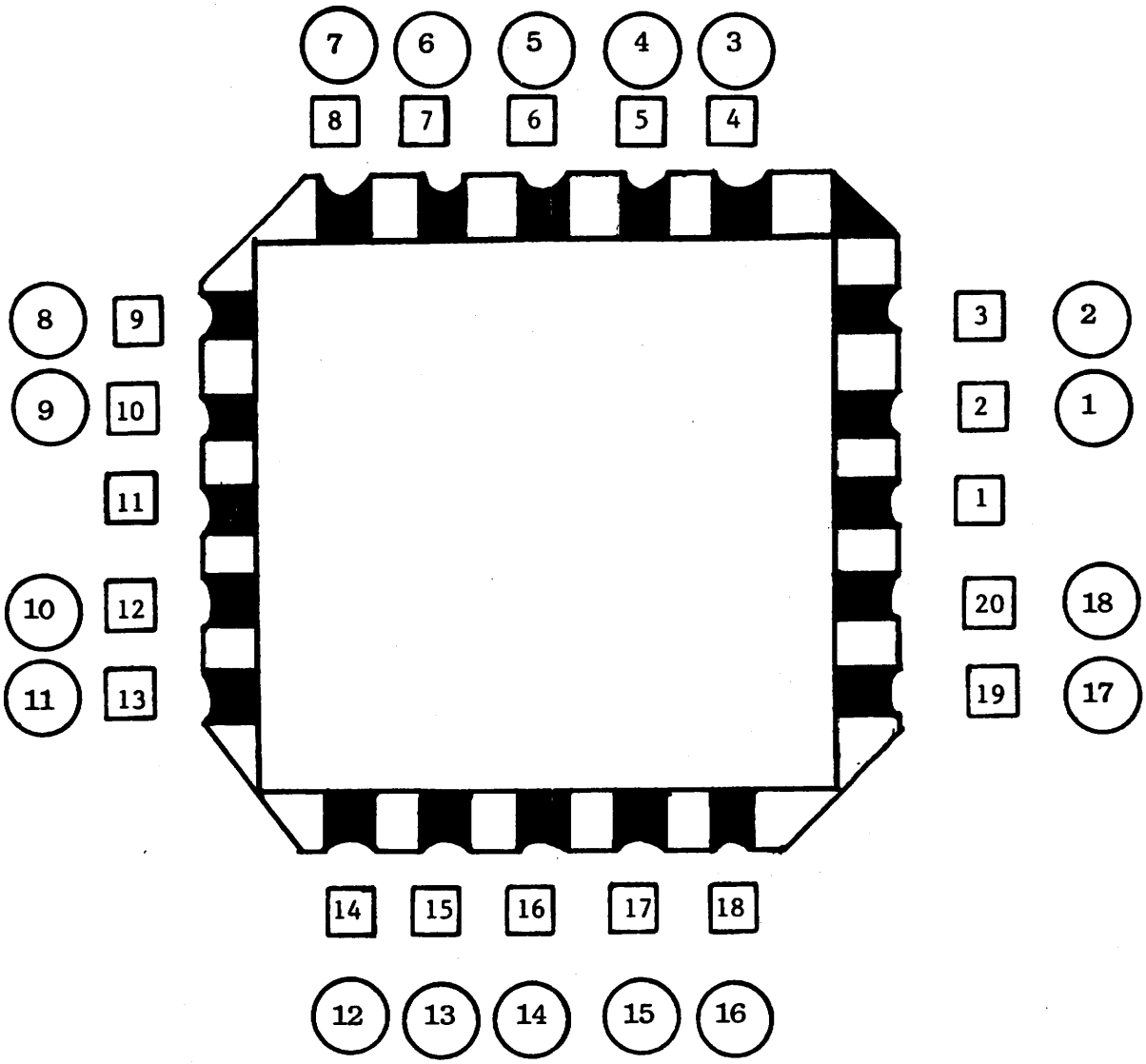
FOR

20 - LEAD CHIP CARRIER

(OPTIONAL VERSION)

(Top View)

FIGURE 4



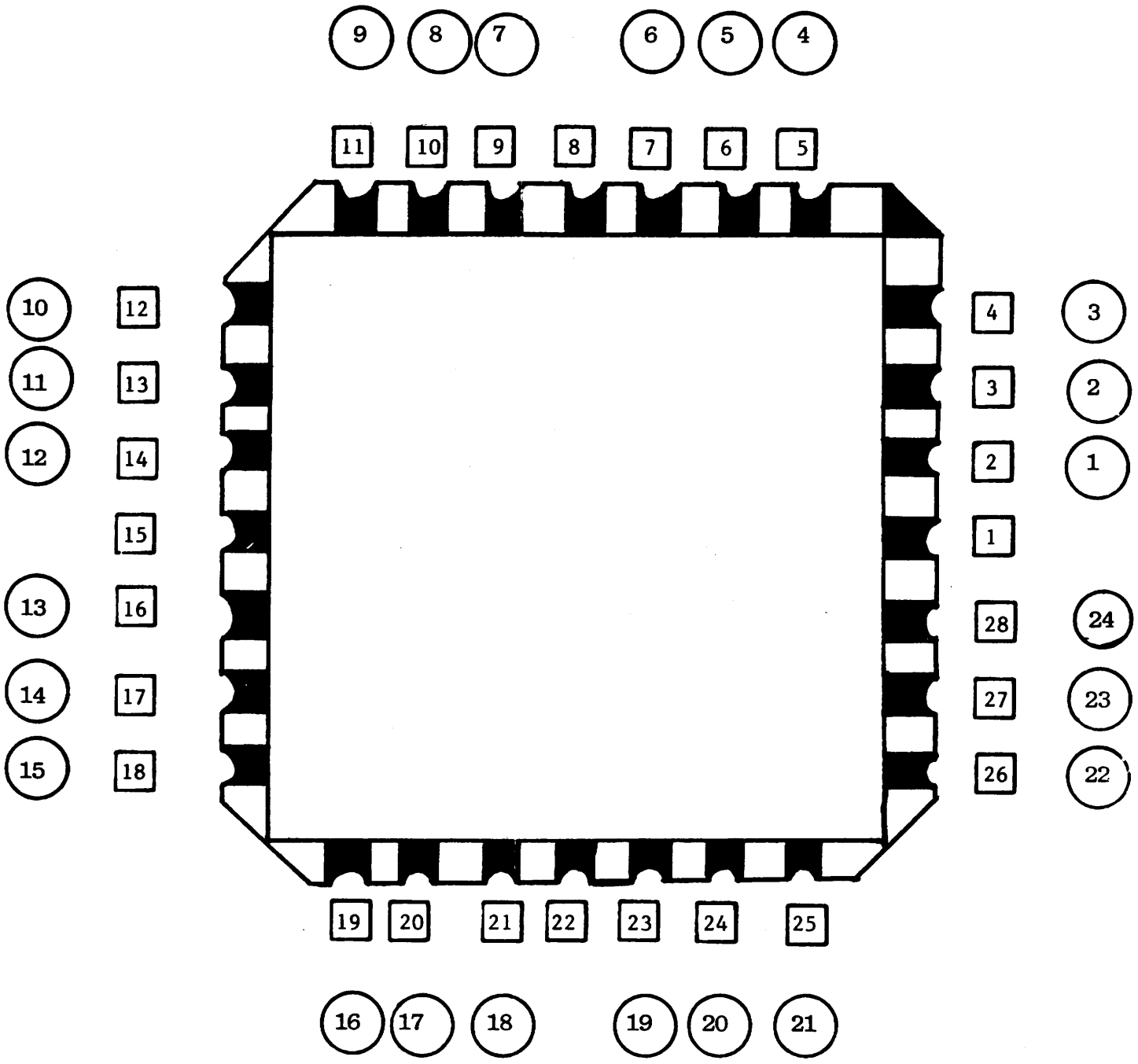
18 - LEAD PIN-OUT

FOR

20 - LEAD CHIP CARRIER

(Top View)

FIGURE 5



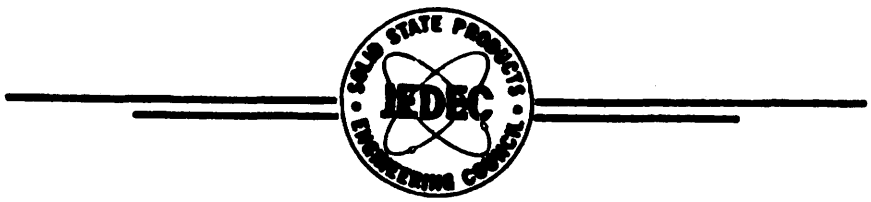
24 - LEAD PIN-OUT

FOR

28 - LEAD CHIP CARRIER

(Top View)

FIGURE 6


SOLID STATE PRODUCTS
JEDEC
ENGINEERING COUNCIL